

Features

- 808nm multi-emitter VCSEL chip
- Number of emitters: 39
- Power Conversion Efficiency (PCE): 26%
- Low threshold current
- Typical 350mW output power at 475mA
- Chip size: 294um x 278um
- Chip thickness: 100um

Applications

- 3D sensors
- Lidars
- IR illuminations
- Medical application
- Solid-state pump source

Specifications

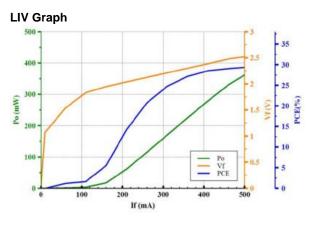
Absolute Maximum Ratings									
Parameters	Symbol	Rating	Unit	Conditions					
Case Operating Temperature	Тор	Top -40 to 85							
Storage Temperature	Tstg	-40 to 105	°C						
Reflow Soldering Temperature	Tsol	320	°C	10 seconds					
Reverse Voltage	Vr	5	V						
Maximum Continuous Current	Imax	750	mA						
ESD Exposure (Human Body) Model	ESD	2K	V						

Electro-Optical Characteristics (Top=25°C, Pulse width 0.1ms, duty cycle 1%)

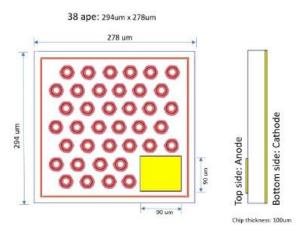
Lieuro-Optical Onaracteristics (10p=25 0, 1 dise width 0.1113, ddty cycle 170)								
Parameters	Symbol	Min.	Тур.	Max.	Unit	Conditions		
Optical Output Power	Po	-	350	-	mW	I _F =475mA		
Forward Current	lF	-	475	-	mA			
Threshold Current	Ith	-	60	-	mA			
Forward Voltage	VF	-	2.5	-	V	I _F =475mA		
Power Conversion Efficiency	PCE	-	26	-	%	I _F =475mA		
Slope Efficiency	η	-	1.09	-	mW/mA	P _o =350mW		
Peak Wavelength	λρ	800	808	816	nm	I _F =475mA		
Series Resistance	Rs	-	1.74	-	Ohm	I _F =475mA		
Wavelength Temperature Drift	Δλρ/ ΔΤ	-	0.07	-	nm/°C	I _F =475mA		
Beam Divergence	FWHM B	-	25	-	deg			
Emission Area			231x210		um ²			
Number of Emission Aperture		-	38	-				

Note: Electro-optical characteristic with a package or diffuser would require further evaluation. Values are based on limited sample size and estimated values.

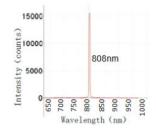
Typical Characteristics



Outline Diagram (unit: um)



Typical Spectral Width



- Chip size: 294um x 278um
- Chip thickness: 100um
- No. emission aperture: 38

Additional Notes

- Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or other conditions above those indicated in the operations section for expanded periods of time may affect reliability.
- In its maximum rating diode laser operation could damage its performance or cause potential safety hazard such as equipment failure.
- Electrostatic discharge is the main reason for laser fault of the diode. Take effective precautions against ESD. When dealing with laser diodes, use wrist strap, grounding work surface and strict antistatic technology.
- The inherent design of this component causes it to be sensitive to electrostatic discharge (ESD). To prevent ESD-induced damage and/or degradation to equipment, take normal ESD precautions when handling this product.
- Specifications are subject to change without notice.